

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	((("5521123") or ("6429506") or ("5789307") or ("6255741") or ("4483194") or ("5095752")).PN.	USPAT; USOCR	OR	OFF	2005/10/29 14:38
L2	169	(@ad<"20020506") and (wafer with cap\$1) and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:47
L3	1	("6716666").PN.	USPAT; USOCR	OR	OFF	2005/10/29 14:39
L4	48	L2 and ((semiconductor or silicon or "si" or ("same" near material) or "same") with (mold or molding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 14:57
L5	1	("5915168").PN.	USPAT; USOCR	OR	OFF	2005/10/29 14:57
L6	7	("4990814" "5059848" "5567656" "5583373" "5593927" "5604160" "5610431").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/29 15:08
L7	70	("5915168").URPN.	USPAT	OR	OFF	2005/10/29 15:18
L8	25	"0207385"	EPO; DERWENT	OR	OFF	2005/10/29 15:19
L9	0	"0207385"	EPO	OR	OFF	2005/10/29 15:20
L10	106	sacmi	EPO	OR	OFF	2005/10/29 15:21
L11	0	maccanici	EPO	OR	OFF	2005/10/29 15:21
L12	7	meccanici	EPO	OR	OFF	2005/10/29 15:21
L13	102	(@ad<"20020506") and (wafer with (scale and cap\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:31
L14	85	L13 not silverbrook	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:33
L15	158	L2 not L14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:33

L16	113	L15 not L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:34
L17	7	("3714370" "3838094" "4303934" "4305897" "4535350").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/29 15:43
L18	64	("4701999").URPN.	USPAT	OR	OFF	2005/10/29 15:43
L19	1887	(@ad<"20020506") and ((upper and lower) with die\$1) and cap\$1 and (wafer or chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:48
L20	611	(@ad<"20020506") and ((upper and lower) near die\$1) and cap\$1 and (wafer or chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:10
L21	610	L20 not L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:49
L22	177	L21 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 15:49
L23	0	(@ad<"20020506") and ((upper and lower) near die\$1) and (((chip or die or wafer)) near (cap\$1 or lid\$1)) and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:12
L24	0	(@ad<"20020506") and ((upper and lower) near die\$1) and (wafer near (cap\$1 or lid\$1)) and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:13
L25	0	(@ad<"20020506") and ((upper and lower) near die\$1) and (wafer near (cap\$1 or lid\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:13

L26	11436	(@ad<"20020506") and ((upper and lower) near die\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:13
L27	0	L26 and (wafer adj cap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:14
L28	81	L26 and wafer and (cap or caps or lid or cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:14
L29	71	L28 not L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/29 16:15